

Power Module Packaging with Double Sided Planar Interconnection and H/E

Disclosure Number

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Technology Summary

A set of advanced packaging technology for manufacturing power modules as a unit construction, offering ultra low electric parasitics, ultra low thermal resistance and higher reliability for high temperature operation through advanced cooling designs, with cost effective and simple fabrication processes using readily available and proven technologies. The set of advanced packaging technology for power modules has easy inverter converter integration, and in turn, will increase the efficiency, density and economy of the application systems.

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